

Electronic Acknowledgement Receipt

EFS ID:	1416698
Application Number:	10711418
International Application Number:	
Confirmation Number:	5417
Title of Invention:	NON-DESTRUCTIVE EVALUATION OF MICROSTRUCTURE AND INTERFACE ROUGHNESS OF ELECTRICALLY CONDUCTING LINES IN SEMICONDUCTOR INTEGRATED CIRCUITS IN DEEP SUB-MICRON REGIME
First Named Inventor/Applicant Name:	Fen Chen
Customer Number:	30449
Filer:	Jack P. Friedman/Terri Fischer
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part/.zip	Pages (if appl.)
1	Applicant summary of interview with examiner	BUR920040182US1_ResponsetoInterviewSummary_12-27-06.pdf	22697	no	1

Warnings:

Information:	Total Files Size (in bytes):	22697
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<u>New Applications Under 35 U.S.C. 111</u>		
If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.		
<u>National Stage of an International Application under 35 U.S.C. 371</u>		
If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.		